# MGV252012S2R2M-10

# PHYSICAL DIMENSIONS:

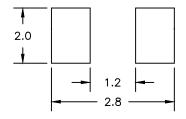
A 2.50	土	0.20
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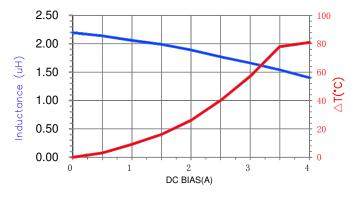
 $B 2.00 \pm 0.20$ 

C 1.20 Max.

 $D = 0.60 \pm 0.30$ 

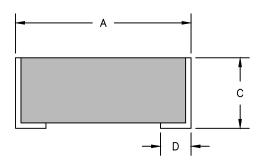
### LAND PATTERNS FOR REFLOW SOLDERING



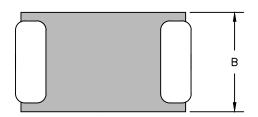


# ELECTRICAL SPECIFICATION @ 25°C

	Min	Norm	Max
INDUCTANCE (uH) L @ 1MHz/1mA ±20%	1.76	2.20	2.64
DCR $(\Omega)$		0.074	0.089
Saturation Current Isat (A)		3.50	3.20
Heating Current Irms (A)		2.50	2.20







#### NOTES:

- 1. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 2. TERMINATION FINISH IS 100% TIN.
- 3. OPERATING TEMPERATURE RANGE:  $-40^{\circ}C \sim +125^{\circ}C$ .
- 4. STORAGE TEMPERATURE RANGE:  $-50^{\circ}$ C  $\sim +125^{\circ}$ C.
- 5. ISat MEANS THAT MAX DC CURRENT WILL CAUSE A PROXIMATELY 30% INDUCTANCE REDUCTION FROM INITIAL VALUE.
- 6. Irms MEANS THAT MAX DC CURRENT WILL CAUSE PROXIMATELY 40°C TEMPERATURE RISE FROM 25±5°C AMBIENT.

DIMENSIONS ARE IN mm.		This print is the property of Laird							
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